

Application No.: 10/901,500

Docket No.: JCLA7208

In The Claims:

Claim 1 (currently amended) A method of laminating copper foil onto a substrate of printed circuit board, the steps of the method comprising:

providing a substrate having an upper surface and a lower surface;

coating isolating material onto the upper surface and the lower surface of the substrate by using a rolling process;

performing a curing process to allow the isolating material to form isolating layers with a predetermined thickness on the upper surface and the lower surface of the substrate; and

laminating metal foils onto the isolating layers formed on the ~~upper and lower surfaces of the substrate~~ surfaces of the isolating layers.

Claim 2 (original) The method of claim 1, wherein the substrate is made of flame-retardant epoxy-glass fabric composite resin (FR-4, FR-5) or bismaleimide-triazine (BT).

Claim 3 (original) The method of claim 1, wherein the isolating material comprises liquid epoxy resin.

Claim 4 (original) The method of claim 1, wherein the isolating material comprises polymer.

Claim 5 (original) The method of claim 1, wherein the isolating material comprises polyimide.

Claim 6 (original) The method of claim 1, wherein a thickness of the isolating layers is controlled by equipment parameters regardless of the type of the metal foil that is used.

Claim 7 (original) The method of claim 1, wherein the metal foil comprises copper foil.

Claim 8 (original) The method of claim 7, wherein the types of the copper foil comprise high profile copper foil, low profile copper foil or reverse copper foil.

(Claims 10-24 have been renumbered as claims 9-23, respectively.)

Claims 9 (canceled)

Claim 10 (withdrawn)

Claim 11 (withdrawn).

Claims 12 (canceled)

Claim 13 (currently amended) A method of laminating copper foil onto a substrate of a printed circuit board, the steps of the method comprising:

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providing a substrate having an upper surface and a lower surface;
coating isolating material onto the upper surface and the lower surface of the substrate by using a rolling process;
performing a curing process to allow the isolating material to form isolating layers with a predetermined thickness on the upper surface and the lower surface of the substrate;
~~laminating metal foils onto the upper surface and the lower surface of the substrate~~
surfaces of the isolating layers; and
performing heating and pressurization processes to secure the metal foils to the surfaces ~~of the substrate~~ the isolating layers.

Claim 14 (original) The method of claim 13, wherein the substrate is made of flame-retardant epoxy-glass fabric composite resin (FR-4, FR-5) or bismaleimide-triazine (BT).

Claim 15 (original) The method of claim 13, wherein the isolating material comprises liquid epoxy resin.

Claim 16 (original) The method of claim 13, wherein the isolating material comprises polymer.

Claim 17 (original) The method of claim 13, wherein the isolating material comprises polyimide.

Claim 18 (original) The method of claim 13, wherein the metal foil comprises copper foil.

Claim 19 (original) The method of claim 18, wherein the types of the copper foil comprise high profile copper foil, low profile copper foil or reverse copper foil.

Claim 20 (currently amended) The method of claim 13, wherein the thickness of the adhesive isolating layers is controlled by equipment parameters regardless of the type of the metal foil that is used.

Claims 21 (canceled)

Claim 22 (withdrawn)

Claim 23 (withdrawn)